

HIGH PERFORMANCE THERMAL GREASE MATERIAL NK Series

Description

Thermal grease (NK series) is a thermal interface material developed by DS to meet the current and future thermal management requirements of high performance microprocessors. It is used to increase heat sink effectiveness by closing the air gap existing between the top of the processor and the heat sink. Air is a thermal insulator with a thermal conductivity of 0.027W/mK. The grease is applied to the raised area on top of the processor after the processor is in the socket.

Typical Application

- ▶ Flip chip microprocessors
- ▶ IGBA and Power supplies
- ▶ Graphic chips, DSP chips
- ▶ LED solid state lighting
- ▶ High-wattage electronic components



GPU, HEAT PIPE, CPU, LED...

TIM – Grease						
Property	NK10	NK7	NK5	NK3	Unit	Test Method
Color Appearance	Dark Gray	Dark Gray	Gray	White	---	Visual
Viscosity(25°C)	15~17	15~17	15~17	14~16	10 ⁴ cps	ASTM D2196
Specific gravity(25°C)	3.4	3.4	3.3	2.7	g/cc	ASTM D792
Volatile Content (150°C/24hr)	0.1	0.1	0.12	0.21	%	ASTM E595
Oil Release (150°C/24hr)	0.02	0.02	0.03	0.33	%	---
Thermal Conductivity	10	7	5	3	W/m*k	ASTM D5470
Continuous Use Temp	-40~180				°C	---

Production Procedure

